

## N-Ch 100V Fast Switching MOSFETs

### Features

- Advanced Trench MOS Technology
- 100% EAS Guaranteed
- Fast Switching Speed
- Green Device Available

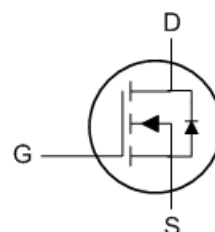
### Applications

- Portable Equipment.
- Battery Powered Systems.
- Hard Switching and High-Speed Circuit.

### Product Summary

| BVDSS | RDSON | ID  |
|-------|-------|-----|
| 100V  | 20mΩ  | 38A |

### TO252 Pin Configuration



### Absolute Maximum Ratings

| Symbol                          | Parameter                                  | Rating     | Units            |
|---------------------------------|--------------------------------------------|------------|------------------|
| $V_{DS}$                        | Drain-Source Voltage                       | 100        | V                |
| $V_{GS}$                        | Gate-Source Voltage                        | $\pm 20$   | V                |
| $I_D @ T_C = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 38         | A                |
| $I_D @ T_C = 100^\circ\text{C}$ | Continuous Drain Current, $V_{GS} @ 10V^1$ | 24         | A                |
| $I_D @ T_A = 25^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 7.6        | A                |
| $I_D @ T_A = 70^\circ\text{C}$  | Continuous Drain Current, $V_{GS} @ 10V^1$ | 6.0        | A                |
| $I_{DM}$                        | Pulsed Drain Current <sup>2</sup>          | 90         | A                |
| EAS                             | Single Pulse Avalanche Energy <sup>3</sup> | 45         | mJ               |
| $I_{AS}$                        | Avalanche Current                          | 30         | A                |
| $P_D @ T_C = 25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>       | 52         | W                |
| $P_D @ T_A = 25^\circ\text{C}$  | Total Power Dissipation <sup>4</sup>       | 2.1        | W                |
| $T_{STG}$                       | Storage Temperature Range                  | -55 to 150 | $^\circ\text{C}$ |
| $T_J$                           | Operating Junction Temperature Range       | -55 to 150 | $^\circ\text{C}$ |

### Thermal Data

| Symbol          | Parameter                                        | Typ. | Max. | Unit               |
|-----------------|--------------------------------------------------|------|------|--------------------|
| $R_{\theta JA}$ | Thermal Resistance Junction-Ambient <sup>1</sup> | ---  | 60   | $^\circ\text{C/W}$ |
| $R_{\theta JC}$ | Thermal Resistance Junction-Case <sup>1</sup>    | ---  | 2.4  | $^\circ\text{C/W}$ |

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

| Symbol       | Parameter                                      | Conditions                                                | Min. | Typ. | Max.      | Unit      |
|--------------|------------------------------------------------|-----------------------------------------------------------|------|------|-----------|-----------|
| $BV_{DS}$    | Drain-Source Breakdown Voltage                 | $V_{GS}=0V$ , $I_D=250\mu A$                              | 100  | ---  | ---       | V         |
| $R_{DS(ON)}$ | Static Drain-Source On-Resistance <sup>2</sup> | $V_{GS}=10V$ , $I_D=10A$                                  | ---  | 15.5 | 20        | $m\Omega$ |
|              |                                                | $V_{GS}=4.5V$ , $I_D=10A$                                 | ---  | 21   | 30        |           |
| $V_{GS(th)}$ | Gate Threshold Voltage                         | $V_{GS}=V_{DS}$ , $I_D=250\mu A$                          | 1.2  | 1.8  | 2.2       | V         |
| $I_{DSS}$    | Drain-Source Leakage Current                   | $V_{DS}=80V$ , $V_{GS}=0V$ , $T_J=25^\circ\text{C}$       | ---  | ---  | 1         | $\mu A$   |
|              |                                                | $V_{DS}=80V$ , $V_{GS}=0V$ , $T_J=55^\circ\text{C}$       | ---  | ---  | 5         |           |
| $I_{GSS}$    | Gate-Source Leakage Current                    | $V_{GS}=\pm 20V$ , $V_{DS}=0V$                            | ---  | ---  | $\pm 100$ | nA        |
| $R_g$        | Gate Resistance                                | $V_{DS}=0V$ , $V_{GS}=0V$ , $f=1\text{MHz}$               | ---  | 1    | ---       | $\Omega$  |
| $Q_g$        | Total Gate Charge                              | $V_{DS}=50V$ , $V_{GS}=10V$ , $I_D=10A$                   | ---  | 17.9 | ---       | nC        |
| $Q_{gs}$     | Gate-Source Charge                             |                                                           | ---  | 2.8  | ---       |           |
| $Q_{gd}$     | Gate-Drain Charge                              |                                                           | ---  | 5.2  | ---       |           |
| $T_{d(on)}$  | Turn-On Delay Time                             | $V_{DD}=30V$ , $V_{GS}=10V$ , $R_G=6\Omega$ ,<br>$I_D=1A$ | ---  | 13   | ---       | ns        |
| $T_r$        | Rise Time                                      |                                                           | ---  | 6    | ---       |           |
| $T_{d(off)}$ | Turn-Off Delay Time                            |                                                           | ---  | 30   | ---       |           |
| $T_f$        | Fall Time                                      |                                                           | ---  | 29   | ---       |           |
| $C_{iss}$    | Input Capacitance                              | $V_{DS}=50V$ , $V_{GS}=0V$ , $f=1\text{MHz}$              | ---  | 849  | ---       | pF        |
| $C_{oss}$    | Output Capacitance                             |                                                           | ---  | 185  | ---       |           |
| $C_{rss}$    | Reverse Transfer Capacitance                   |                                                           | ---  | 8    | ---       |           |

**Diode Characteristics**

| Symbol   | Parameter                                | Conditions                                      | Min. | Typ. | Max. | Unit |
|----------|------------------------------------------|-------------------------------------------------|------|------|------|------|
| $I_S$    | Continuous Source Current <sup>1,6</sup> | $V_G=V_D=0V$ , Force Current                    | ---  | ---  | 38   | A    |
| $V_{SD}$ | Diode Forward Voltage <sup>2</sup>       | $V_{GS}=0V$ , $I_S=1A$ , $T_J=25^\circ\text{C}$ | ---  | ---  | 1.2  | V    |

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 20Z copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu s$  , duty cycle  $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}=25V$ ,  $V_{GS}=10V$ ,  $L=0.1mH$ ,  $I_{AS}=30A$
- 4.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$  , in real applications , should be limited by total power dissipation.

## Typical Characteristics

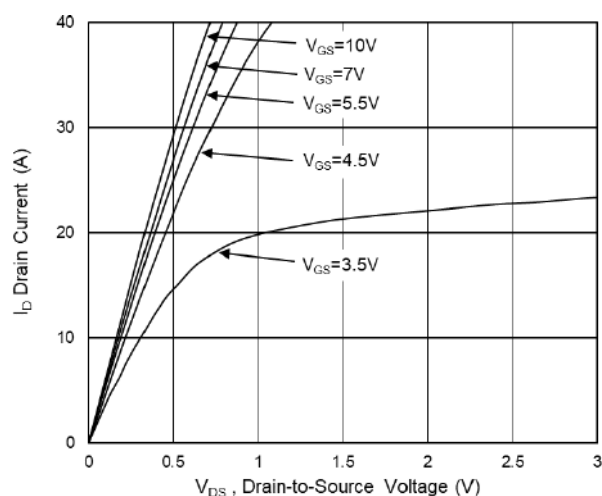


Fig.1 Typical Output Characteristics

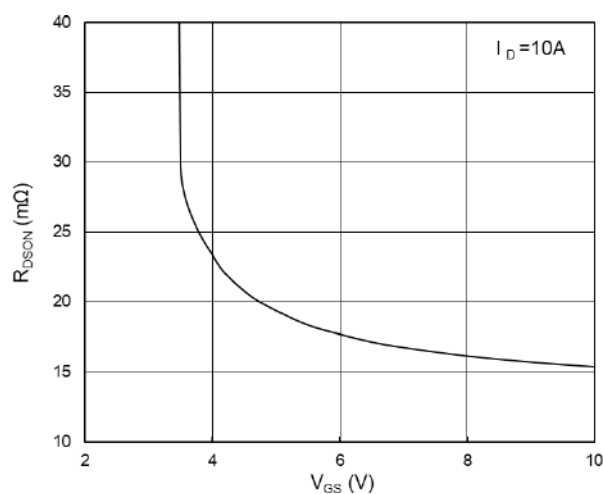


Fig.2 On-Resistance vs G-S Voltage

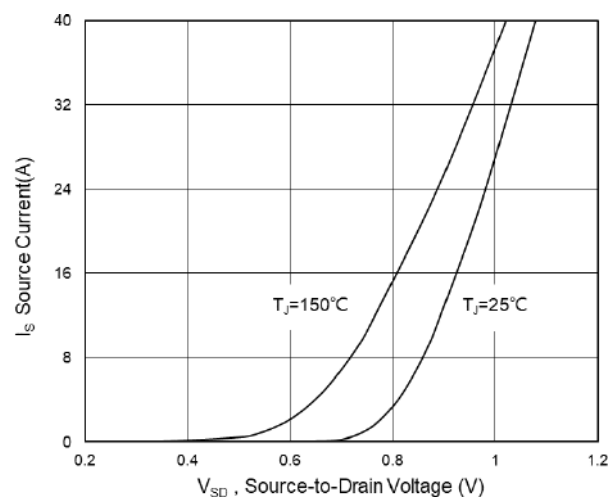


Fig.3 Source Drain Forward Characteristics

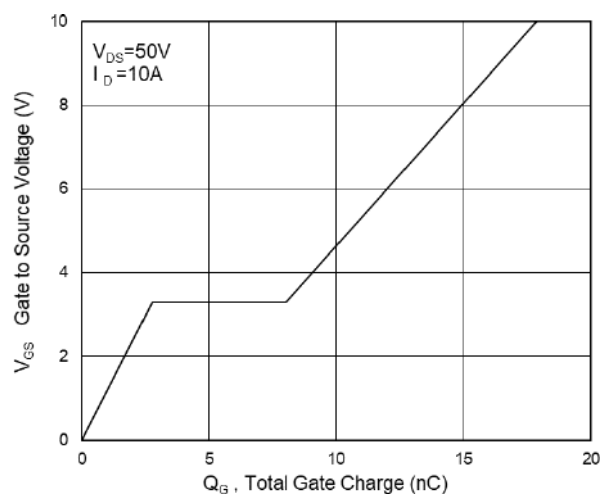


Fig.4 Gate-Charge Characteristics

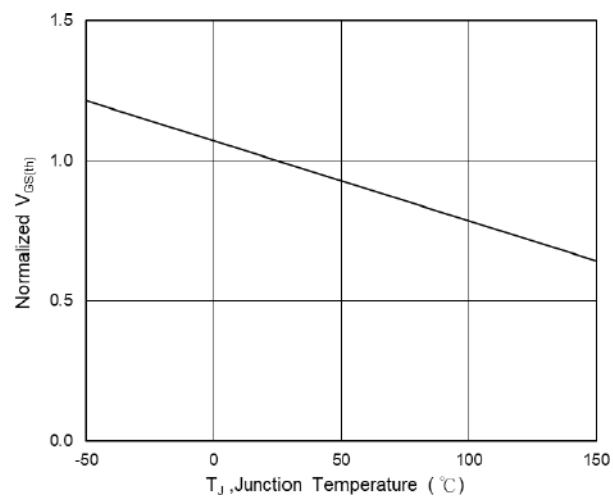


Fig.5 Normalized  $V_{GS(th)}$  vs  $T_J$

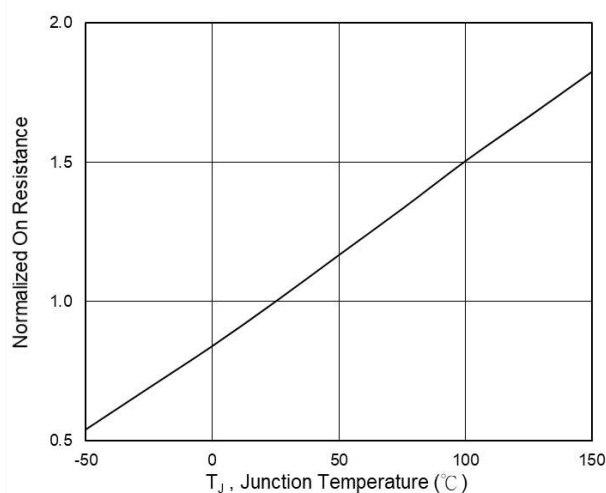
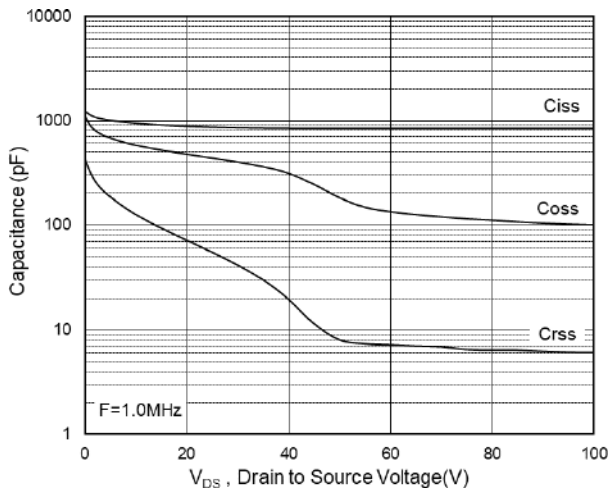
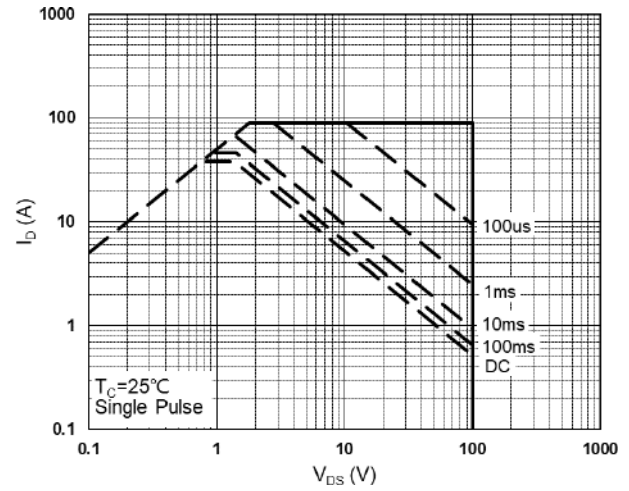


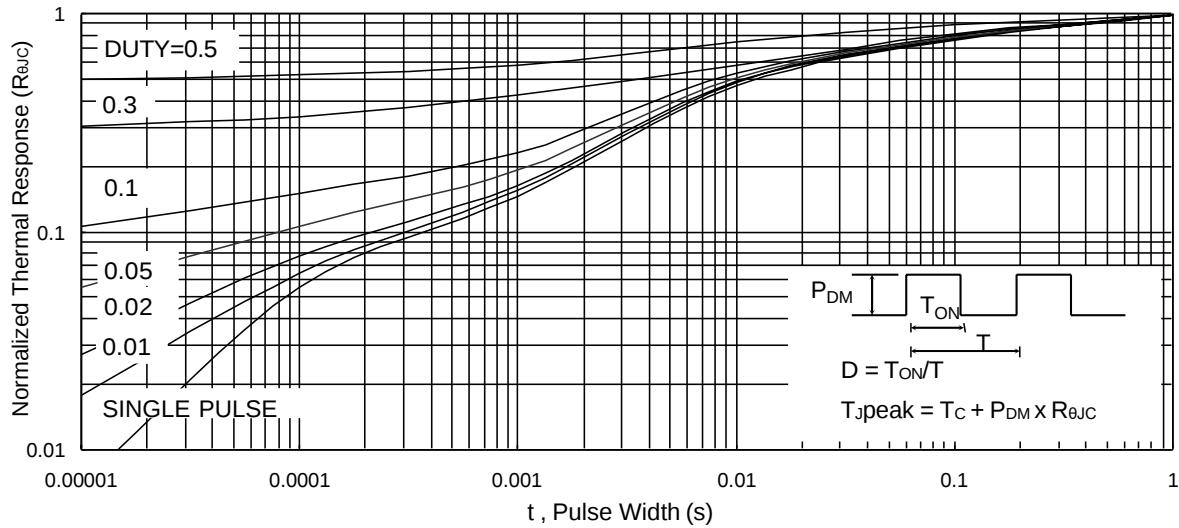
Fig.6 Normalized  $R_{DS(on)}$  vs  $T_J$



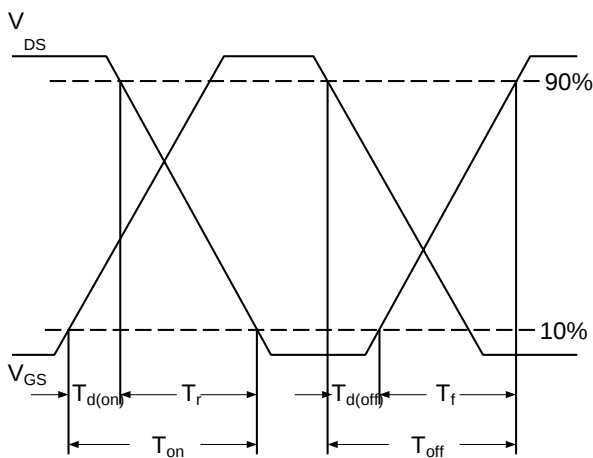
**Fig.7 Capacitance**



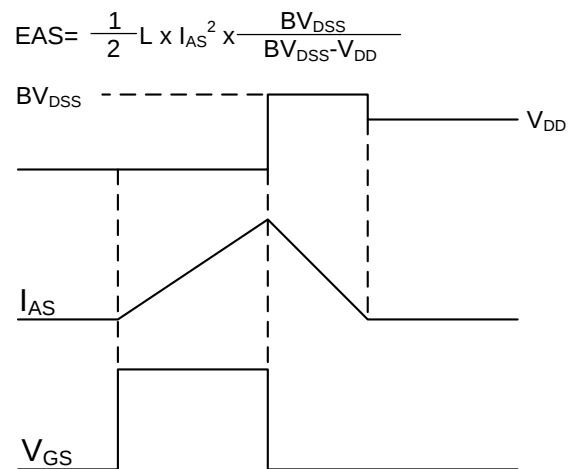
**Fig.8 Safe Operating Area**



**Fig.9 Normalized Maximum Transient Thermal Impedance**



**Fig.10 Switching Time Waveform**



**Fig.11 Unclamped Inductive Waveform**